

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kazumasa Ogasawara</td> <td>07/26/2013</td> </tr> <tr> <td>Kazuo Teramoto</td> <td>07/26/2013</td> </tr> <tr> <td>Yuji Ueda</td> <td>07/31/2013</td> </tr> <tr> <td>Yasushi Itoh</td> <td>07/26/2013</td> </tr> <tr> <td>Hirohito Ishigaki</td> <td>07/26/2013</td> </tr> </tbody> </table>		Name	Execution Date	Kazumasa Ogasawara	07/26/2013	Kazuo Teramoto	07/26/2013	Yuji Ueda	07/31/2013	Yasushi Itoh	07/26/2013	Hirohito Ishigaki	07/26/2013
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RECEIVING PARTY DATA													
Name:	Shiga University of Medical Science												
Street Address:	Setatsukinowa-cho, Otsu-shi												
City:	Shiga												
State/Country:	JAPAN												
Postal Code:	5202192												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14008538</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14008538								
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CORRESPONDENCE DATA													
Fax Number:	2027393001												
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Signature:	/H. Janice Lee/												

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Date:

10/01/2013

Total Attachments: 2

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ASSIGNMENT

WHEREAS I/WE, the below named inventors, [hereinafter referred to as Assignors], have made an invention entitled:

**IMMUNOSUPPRESSIVE CELL-CAPTURING MATERIAL AND IMMUNOSUPPRESSIVE CELL-CAPTURING COLUMN**

for which I/WE filed an application for United States Letters Patent on \_\_\_\_\_ (Application No. \_\_\_\_\_); and

WHEREAS, SHIGA UNIVERSITY OF MEDICAL SCIENCE, whose post office address is Setatsukinowa-cho, Otsu-shi, Shiga 5202192, Japan (hereinafter referred to as the Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the applications for and United States Letters Patent to be issued on this invention and the applications for and Letters Patent to be issued on this invention from any other country;

NOW THEREFORE, be it known that, for good and valuable consideration in hand paid and other good and valuable consideration, the receipt of which from the assignee is hereby acknowledged, I/WE, as assignor, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, their lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and the listed applications, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which have been or may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to the assignee, their successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/WE have the full right to convey the interest assigned by this Assignment, and I/WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with the assignee, their successors and assigns, any facts known to ME/US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said assignee, their successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid the assignee, their successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, their successors and assigns.

IN TESTIMONY WHEREOF, I/We have hereunto set our hand.

	<u>Kazumasa OGASAWARA</u> Full Name of First Assignor
SS.	<u>c/o Shiga University of Medical Science, Setatsukinowa-cho, Otsu-shi, Shiga 5202192, Japan</u> Address
	<u>Kazumasa Ogasawara</u> First Assignor's Signature
	<u>7/26/13</u> Date

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Full Name of Second Assignor

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Second Assignor's Signature

7/26/13  
Date

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Full Name of Third Assignor

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Yuji Ueda  
Third Assignor's Signature

7/31/13  
Date

**Yasushi ITOH**

Full Name of Fourth Assignor

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Address

Yasushi Itoh  
Fourth Assignor's Signature

7/26/2013  
Date

**Hirohito ISHIGAKI**

Full Name of Fifth Assignor

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Address

Hirohito Ishigaki  
Fifth Assignor's Signature

7/26/13  
Date